



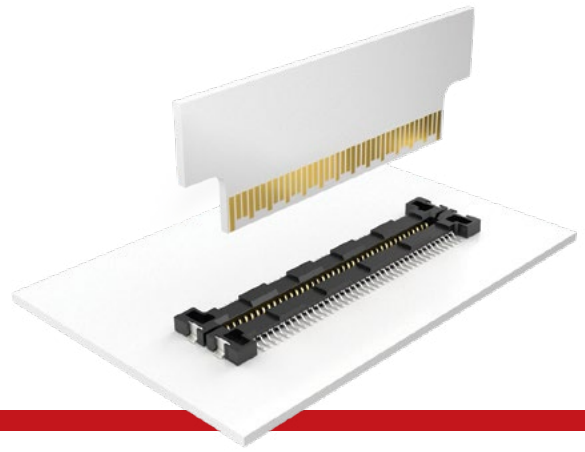
**THE DATASHEET OF
SAL1-127-01-H-S-A**



HIGH-SPEED THROUGH BOARD SOCKET

(1.00 mm) .0394" PITCH • SAL1 SERIES

14
Gbps



SAL1

Card Mates:

(1.60 mm) .062" or
(2.36 mm) .093" card

SPECIFICATIONS

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over 50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

2.9 A per pin
(2 adjacent pins powered)

PROCESSING

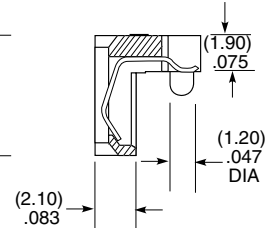
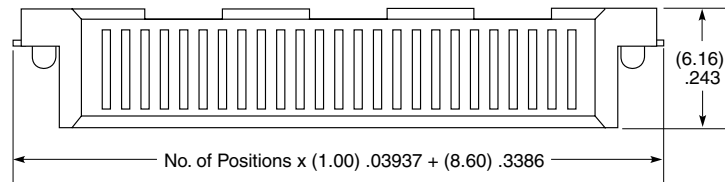
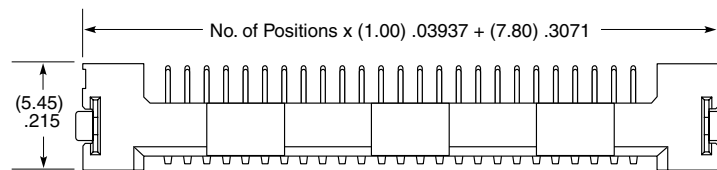
Lead-Free Solderable:

Yes

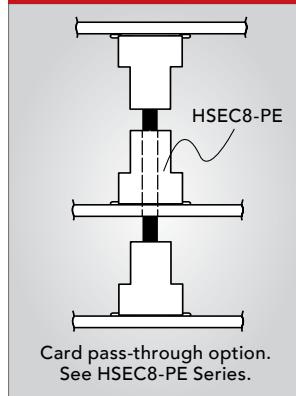
SMT Lead Coplanarity:

(0.10 mm) .004" max

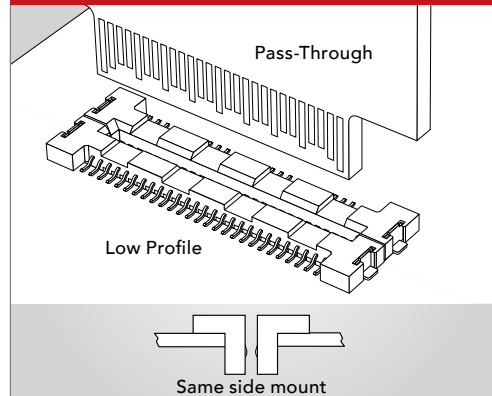
SAL1	-	1	NO. OF POSITIONS	-	01	PLATING OPTION	-	S	-	A	-	OPTION
			-20, -27, -30, -40			-S = 30 μ" (0.76 μm) Gold on contact, Matte tin on tail						-TR = Tape & Reel -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)



OTHER SOLUTION



APPLICATIONS



Notes:



While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications..

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?SAL1

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View SAL1-127-01-H-S-A on WIN SOURCE](#)
-  [Samtec Inc. Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

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-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management